Attorney's Docket No. SON-2010

## DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION English Language Declaration

As below named inventors, we hereby declare that:  Our residence, post office address and citizenship are as stated below next to our names.  We believe we are the original, first and joint inventors of the subject matter wh claimed and for which a patent is sought on the invention entitled THIN FIME CONCONDUCTOR DEVICE, DISPLAY DEVICE USING SUCH THIN FILM SEMICONDUCTOR DEVICE USING SUCH	Our resider names.  We believe claimed and THIN FILM DEVICE AND the specific (check one) is attack was filed Application and was a specification of the spec	we are the original for which a patent SEMICONDUCTOR DEVI D MANUFACTURING MEI Cation of which on Serial No.  mended on ate that I have recon, including the original straightful of the distribution of the di	dress and control of the control of	itizenship are as i joint inventors on the invention y DEVICE USING SU	of the su entitled ICH THIN F	the a	e matter which
We believe we are the original, first and joint inventors of the subject matter whe claimed and for which a patent is sought on the invention entitled THIN FILM SEMICONDUCTOR DEVICE, DISPLAY DEVICE USING SUCH THIN FILM SEMICONDUCTOR DEVICE, DISPLAY DEVICE USING SUCH THIN FILM SEMICONDUCTOR DEVICE DEVICE AND MANUFACTURING METHOD THEREOF the specification of which (check one)  (check one)  (is attached hereto.  was filed on	we believe claimed and THIN FILM DEVICE AN the specific was filed Application and was a specification of the speci	we are the original for which a patent SEMICONDUCTOR DEVI D MANUFACTURING MET cation of which ed hereto.  on on Serial No. mended on ate that I have recon, including the offittle 37, Code of the cod	l, first and t is sought ICE, DISPLATED THEREOF THE CONTROL THE CO	i joint inventors on the invention Province USING SUR	of the su entitled ICH THIN F	the a	e matter which
Claimed and for which a patent is sought on the invention entitled THIN FILM SEMICONDUCTOR DEVICE, DISPLAY DEVICE USING SUCH THIN FILM SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF the specification of which  (check one)  is attached hereto.  was filed on  Application Serial No. and was amended on  I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havifiling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  P2000-023475 Japan 01/02/2000 X  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I sendowledge the duty to disclose material to patentability as defined in Title 37, as provided by a defined in Title 37, as provided by a defined in Title 37, as provided by a defined in Title 37, as provided by the first paragraph of Title 35, United States Code \$112, I sendowledge the duty to disclose material to patentability as defined in Title 37, as provided by a defined in Title 37.	claimed and THIN FILM DEVICE AN the specific attach was filed Application and was a specification of the specific attach was filed and was a specific attach and was a specifi	for which a patent SEMICONDUCTOR DEVI D MANUFACTURING MET cation of which  ed hereto.  on on Serial No. mended on ate that I have revon, including the of gethe duty to disc Title 37, Code of I	t is sought [CE, DISPLA] THOD THEREOF  viewed and to claims, as a close inform	on the invention of DEVICE USING SU	entitled CH THIN F	the a	EMICONDUCTOR  as  as  above identifi
(check one)  is attached hereto.  was filed on  Application Serial No. and was amended on  I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havi filing date before that of the application on which priority is claimed:  Prior Foreign Application(s)  Priority Claimed P2000-023475    Japan	(check one)  is attach  was filed  Applicati  and was a  I hereby st  specificati  I acknowled  defined in	ed hereto.  on  on Serial No.  mended on  ate that I have recon, including the office of the duty to discrete the duty the duty to discrete the duty t	viewed and claims, as a	understand the con	ntents of endment re	the a	bove identifi
Application Serial No.  and was amended on  I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havi filling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  P2000-023475 Japan 01/02/2000 X  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37,	was filed Application and was a second was a second in a constant of the second and the second a	onon Serial No mended on ate that I have rev on, including the o ge the duty to disc Title 37, Code of i	viewed and claims, as a	understand the con	ntents of endment re	the a	bove identifi
Application Serial No. and was amended on  I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havifiling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  P2000-023475 Japan 01/02/2000 X  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37.	Application and was a lineraby standard in lineraby classics.	on Serial No	viewed and claims, as a	understand the con	ntents of endment re	the a	bove identifi
I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate having filing date before that of the application on which priority is claimed:  Prior Foreign Application(s)  Priority Claimed P2000-023475  Japan  Ol/02/2000  X  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37,	and was a I hereby st specificati I acknowled defined in I hereby cl	mended on ate that I have read on, including the of the duty to discrete are the fittle 37, Code of I	viewed and claims, as a	understand the commended by any amo	ntents of endment re	the a	above identified to above.
I hereby state that I have reviewed and understand the contents of the above ident specification, including the claims, as amended by any amendment referred to above I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate having filing date before that of the application on which priority is claimed:  Prior Foreign Application(s)  Priority Claimed  P2000-023475  Japan  O1/02/2000  X  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application (s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37,	and was a I hereby st specificati I acknowled defined in I hereby cl	mended on ate that I have read on, including the of the duty to discrete are the fittle 37, Code of I	viewed and claims, as a	understand the commended by any amo	ntents of endment re	the a	above identified to above.
I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, \$1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havifiling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  P2000-023475    Japan   O1/02/2000   X	I acknowled defined in	on, including the o ge the duty to disc Title 37, Code of 1	claims, as a close inform	amended by any ame	endment re	ererre	above identified to above.
I acknowledge the duty to disclose information which is material to patentability defined in Title 37, Code of Federal Regulations, §1.56.  I hereby claim foreign priority benefits under Title 35, United States Code, §119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havifiling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  Priority Claimed 10000-023475  [Number]  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37,	I acknowled defined in	ge the duty to disc Title 37, Code of I	close inform				
I hereby claim foreign priority benefits under Title 35, United States Code, \$119 foreign application(s) for patent of inventor's certificate listed below and have identified below any foreign application for patent or inventor's certificate havifiling date before that of the application on which priority is claimed:  Prior Foreign Application(s)  P2000-023475  Japan  O1/02/2000  X  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37, acknowledge the duty to disclose material to patentability as defined in Title 37,	I hereby cl			lations, \$1.56.	aterial to	pate	entability as
foreign application(s) for patent of inventor's certificate listed below and nave identified below any foreign application for patent or inventor's certificate havi filing date before that of the application on which priority is claimed:  Prior Foreign Application(s)  Priority Claimed  Priority Claimed  Priority Claimed  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  Test No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  Test No  (Number)  Test No  (Number)  Test No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  Test No  (Nu	foreign and						
P2000-023475 Japan 01/02/2000 X  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  (Number) (Country) (Day/Month/Year Filed) Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, In acknowledge the duty to disclose material to patentability as defined in Title 37,	identified	lication(s) for pathelow any foreign a	tent of inve application	entor's certificat for patent or in	te listed ventor's o	below certif	, and nave als Licate having
(Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, In acknowledge the duty to disclose material to patentability as defined in Title 37,	Prior Fore	gn Application(s)			E	Priori	ty Claimed
(Number)  (Country)  (Day/Month/Year Filed)  Yes No  (Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37,	P2000-0234	75 Japan	•	•		X	
(Number)  (Country)  (Day/Month/Year Filed)  Yes No  We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, It acknowledge the duty to disclose material to patentability as defined in Title 37,	(Number)	(Country)	(Da	y/Month/Year File	<u>3)                                    </u>	(es	No
We hereby claim the benefit under Title 35, United States Code, \$120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, It acknowledge the duty to disclose material to patentability as defined in Title 37,	(Number)	(Country)	(Da)	y/Month/Year File	<u>d)</u>	(es	No
States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application the manner provided by the first paragraph of Title 35, United States Code \$112, I acknowledge the duty to disclose material to patentability as defined in Title 37,	(Number)	(Country)	(Da	y/Month/Year File	<u>a)</u>	(es	No
of the prior application and the national or PCT international filing date of this application:	States applications of the manner acknowledge of Federal	ication(s) listed his application is provided by the first the duty to discharge lations. \$1.56	below and in not discloning the control of the con	nsofar as the subset of the prior of the pri	ject matte United Stat nited Stat y as defir ailable be	er of ates a mes Co med in etween	each of the application in ode \$112, I an Title 37, Contact the filing of
(Application Serial No.) (Filing Date) (Status)	application	:	/ IT 2 ?	ing Data)		15+	atus)
(Ctatue)	application	:	/ 172.7	ing Data)		19+	atus)

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

## English Language Declaration

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Ronald P. Kananen, Reg. No. 24,104; Ralph T. Rader, Reg. No. 28,772; Michael D. Fishman, Reg. No. 31,951, Richard D. Grauer, Reg. No. 22,388; Joseph V. Coppola, Sr., Reg. No. 33,373; Michael B. Stewart, Reg. No. 36,018; Steven L. Nichols, Registration No. 40,326

Send Correspondence to:

Direct telephone calls to:

Ronald P. Kananen, Esq. RADER, FISHMAN & GRAUER The Lion Building 1233 20<sup>th</sup> Street, N.W., Suite 501 Ronald P. Kananen, Esq. (202) 955-3750

20036 Washington, D.C.

Full name of first joint inventor HISAO HAYASHI Date December 26,2000 Inventor's signature Residence KANAGAWA, JAPAN Citizenship **JAPANESE** c/o SONY CORPORATION Post Office Address 7-35, KITASHINAGAWA 6-CHOME, SHINAGAWA-KU, TOKYO, JAPAN Full name of second joint inventor MASAHIRO FUJINO Date January 15. 200 Second Inventor's signature Pasahino KANAGAWA, JAPAN Residence Citizenship JAPANESE c/o SONY CORPORATION Post Office Address 7-35, KITASHINAGAWA 6-CHOME, SHINAGAWA-KU, TOKYO, JAPAN Full name of third joint inventor YASUSHI SHIMOGAICHI Date Vasushi Sumosaich Third Inventor's signature KANAGAWA, JAPAN Residence Citizenship **JAPANESE** c/o SONY CORPORATION Post Office Address 7-35, KITASHINAGAWA 6-CHOME, SHINAGAWA-KU, TOKYO, JAPAN

(Supply similar information and signature for subsequent joint inventors.)

Attorney's Docket Number: SON-2010

Full name of fourth joint i	nventor MAKOTO TAKATOKU	
Inventor's signature	makoto Takatoku	Date January 9, 2001
Residence KANAG	GAWA, JAPAN	,
Citizenship JAPA	NESE	
Post Office Address	c/o SONY CORPORATION 7-35, KITASHINAGAWA 6-CHOME,	SHINAGAWA-KU,
	TOKYO, JAPAN	
Full name of fifth joint inv	rentor	
Fifth Inventor's signature		Date
Residence		
Citizenship JAPA	NESE	
Post Office Address	c/o SONY CORPORATION 7-35, KITASHINAGAWA 6-CHOME,	SHINAGAWA-KU,
	TOKYO, JAPAN	
Full name of sixth joint in	ventor	
Sixth Inventor's signature	~ ,	Date
Residence		
Citizenship JAPA	NESE	
Post Office Address	c/o SONY CORPORATION 7-35, KITASHINAGAWA 6-CHOME,	SHINAGAWA-KU,
	TOKYO, JAPAN	

(Supply similar information and signature for subsequent joint inventors.)